#### 506167455 07/23/2020

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6214192

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Zhi-Cheng Lee	07/21/2020
Kai-Lin Lee	07/21/2020
Wei-Jen Chen	07/21/2020

### **RECEIVING PARTY DATA**

Name:	UNITED MICROELECTRONICS CORP.	
Street Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park		
City:	Hsin-Chu City	
State/Country:	TAIWAN	

# **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16936442

#### CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

3027291562 Phone:

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU

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Address Line 4: **NEW TAIPEI CITY, TAIWAN** 

ATTORNEY DOCKET NUMBER:	NAUP3678USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	07/23/2020

### **Total Attachments: 6**

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**PATENT** REEL: 053286 FRAME: 0191

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PATENT REEL: 053286 FRAME: 0192

# COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

### Title of Invention:

# HIGH VOLTAGE TRANSISTOR STRUCTURE AND METHOD OF FABRICATING THE SAME

As the below named inventor, I hereby declare that: This declaration is directed to:				
☑ The attached application, or				
☐ United States application nu	mber	filed on	, or	
☐ PCT international application	n number	filed on		
The above-identified application was	made or authorized to be ma	ade by me.		
I believe that I am the original invent application.	or or an original joint inventor	of a claimed invention	in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made in this isonment of not more than five	declaration is punisha e (5) years, or both.	able	
In consideration of the payment by	UNITED MICROELECTS CORP.	RONICS having a	postal address of	
No.3, Li-Hsin Road 2, Science	-Based Industrial Park,	Hsin-Chu City 300	, Taiwan, R.O.C.	
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ nd valuable consideration.	5 1.00), the receipt of v	vhich is hereby	
I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.				
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;				
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this on the date(s) indicated.				
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.				

Page 1 of 6

NPO#NAU-P3678-USA:0 CUST#UMCD-2020-0135

## Docket No NAUP3678USA

Inventor: Zhi-Cheng Lee Date: JUL 2 1 2020

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# COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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☑ The attached application, or			
☐ United States application nu	mber	filed on	, or
☐ PCT international application	number	filed on	
The above-identified application was	made or authorized to be m	ade by me.	
I believe that I am the original invente application.	or or an original joint invento	r of a claimed invention i	in the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impri	I false statement made in thi isonment of not more than fi	s declaration is punishab ve (5) years, or both.	ble
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No.3, Li-Hsin Road 2, Science	-Based Industrial Park	, Hsin-Chu City 300,	Taiwan, R.O.C
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an		(\$ 1.00), the receipt of wh	nich is hereby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, and I hereby covenant that no assignment	nd to any and all improvemention and, in and to, all Letter rany continuations, continuand ad as to Letters Patent any re	nts which are disclosed in s Patent to be obtained for tion-in-part, divisions, re- eissue or re-examination	n the for said newals, thereof.
entered into which would conflict with	nt, sale, agreement or encum nthis assignment;	ibrance has been or will	be made of
I further covenant that ASSIGNEE w and documents relating to said inven known and accessible to I and will te related thereto and will promptly exe	ition and said Letters Patent stify as to the same in any ir	and legal equivalents as iterference, litigation prod	may be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	lication, said invention and s cessary or desirable to carry	said Letters Patent and s out the proposes thereo	of.
Note: An application data sheet (PTC	D/SB/14 or equivalent), inclu	ding naming the entire	

Page 3 of 6

inventive entity, must accompany this form. Use this form for each additional inventor.

NPO#NAU-P3678-USA:0 CUST#UMCD-2020-0135

## Docket No NAUP3678USA

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Kai-Lin Lee	Date:	JUL 2 1 2020	
Signature:	Leilinder.		-	

Page 4 of 6

# COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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☐ United States application nu	mber	filed on	, or		
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The above-identified application was	made or authorized to be made	e by me.			
I believe that I am the original invent application.	or or an original joint inventor of	a claimed invention in	ı the		
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made in this de isonment of not more than five (	eclaration is punishable 5) years, or both.	е		
In consideration of the payment by	UNITED MICROELECTRO	NICS having a po	ostal address of		
No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hs	sin-Chu City 300, 7	Гаiwan, R.O.C		
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ 1 and valuable consideration.	.00), the receipt of whi	ich is hereby		
I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvements to ton and, in and to, all Letters Par any continuations, continuation	which are disclosed in atent to be obtained fo i-in-part, divisions, ren	the r said ewals.		
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;					
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal					
representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this on the date(s) indicated.					
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire					

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inventive entity, must accompany this form. Use this form for each additional inventor.

NPO#NAU-P3678-USA:0 CUST#UMCD-2020-0135

### Docket No NAUP3678USA

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	Wei-Jen Chen	Date:	JUL 2 1 2020		
Signature:	Wei-Jen Chen				

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NPO#NAU-P3678-USA:0 CUST#UMCD-2020-0135

**RECORDED: 07/23/2020** 

F#NPO-P0002E-US1201 DSB0-109U019868

PATENT REEL: 053286 FRAME: 0198